

# SOT910-1

plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; body 6 x 5 x 0.85 mm

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN20
<b>Package type industry code</b>	HVQFN20
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>JEDEC package outline code</b>	MO-220
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	11-10-2005

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.9	-	5	5.1	mm
E	package width	5.9	-	6	6.1	mm
A	seated height	[tbd]	-	0.85	1	mm
A <sub>2</sub>	package height	[tbd]	-	0.85	[tbd]	mm
n <sub>2</sub>	actual quantity of termination	-	-	20	-	

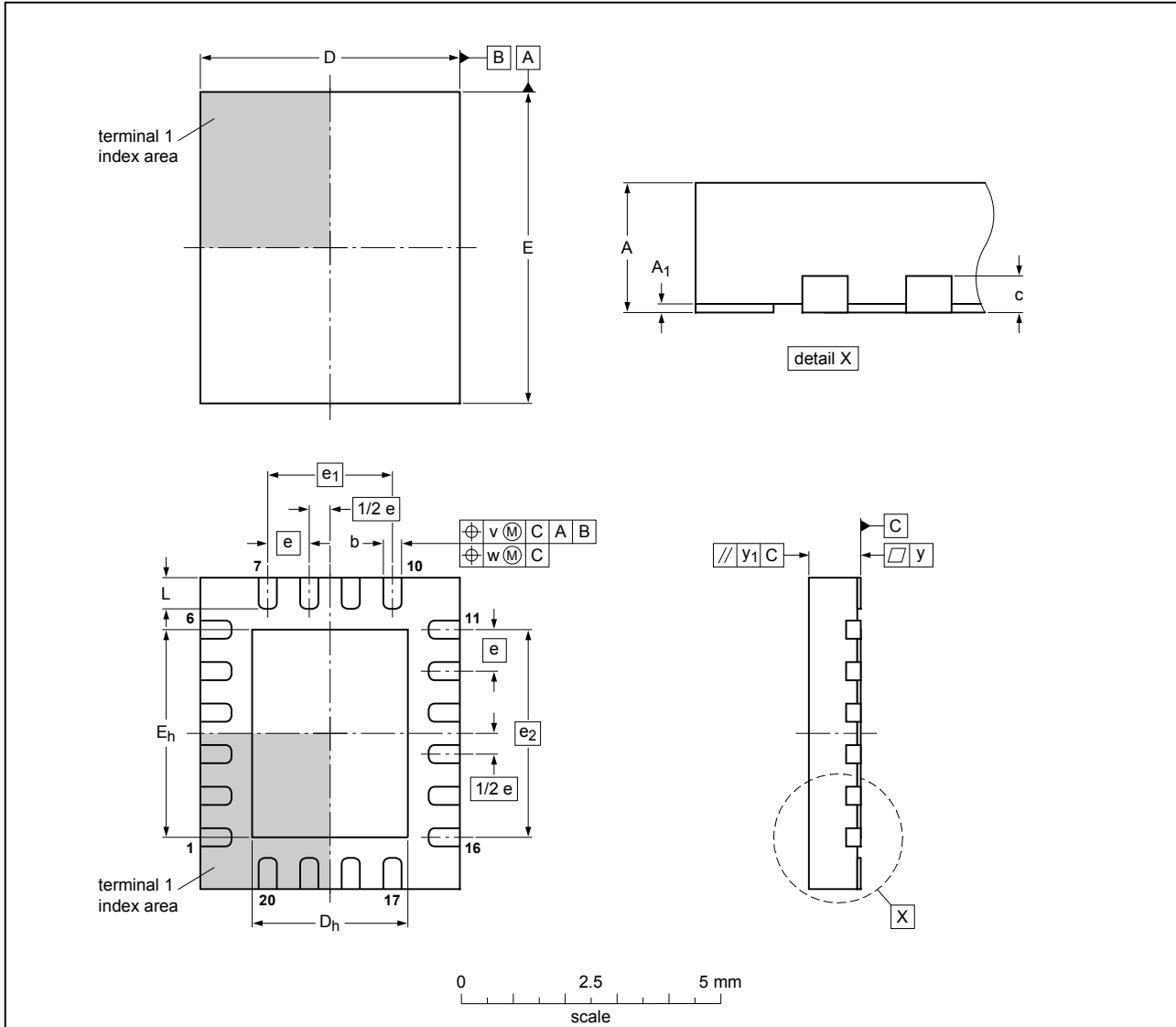


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## 2. Package outline

HVQFN20: plastic thermal enhanced very thin quad flat package; no leads; 20 terminals; body 6 x 5 x 0.85 mm

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**DIMENSIONS** (mm are the original dimensions)

UNIT	A <sub>max</sub>	A <sub>1</sub>	b	c	D	D <sub>h</sub>	E	E <sub>h</sub>	e	e <sub>1</sub>	e <sub>2</sub>	L	v	w	y	y <sub>1</sub>
mm	1	0.05 0.00	0.4 0.3	0.2	5.1 4.9	3.15 2.85	6.1 5.9	4.15 3.85	0.8	2.4	4	0.65 0.40	0.1	0.05	0.05	0.1

**Note**

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT910-1	---	MO-220	---			05-10-11

Fig. 1. Package outline HVQFN20 (SOT910-1)

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### 3. Soldering

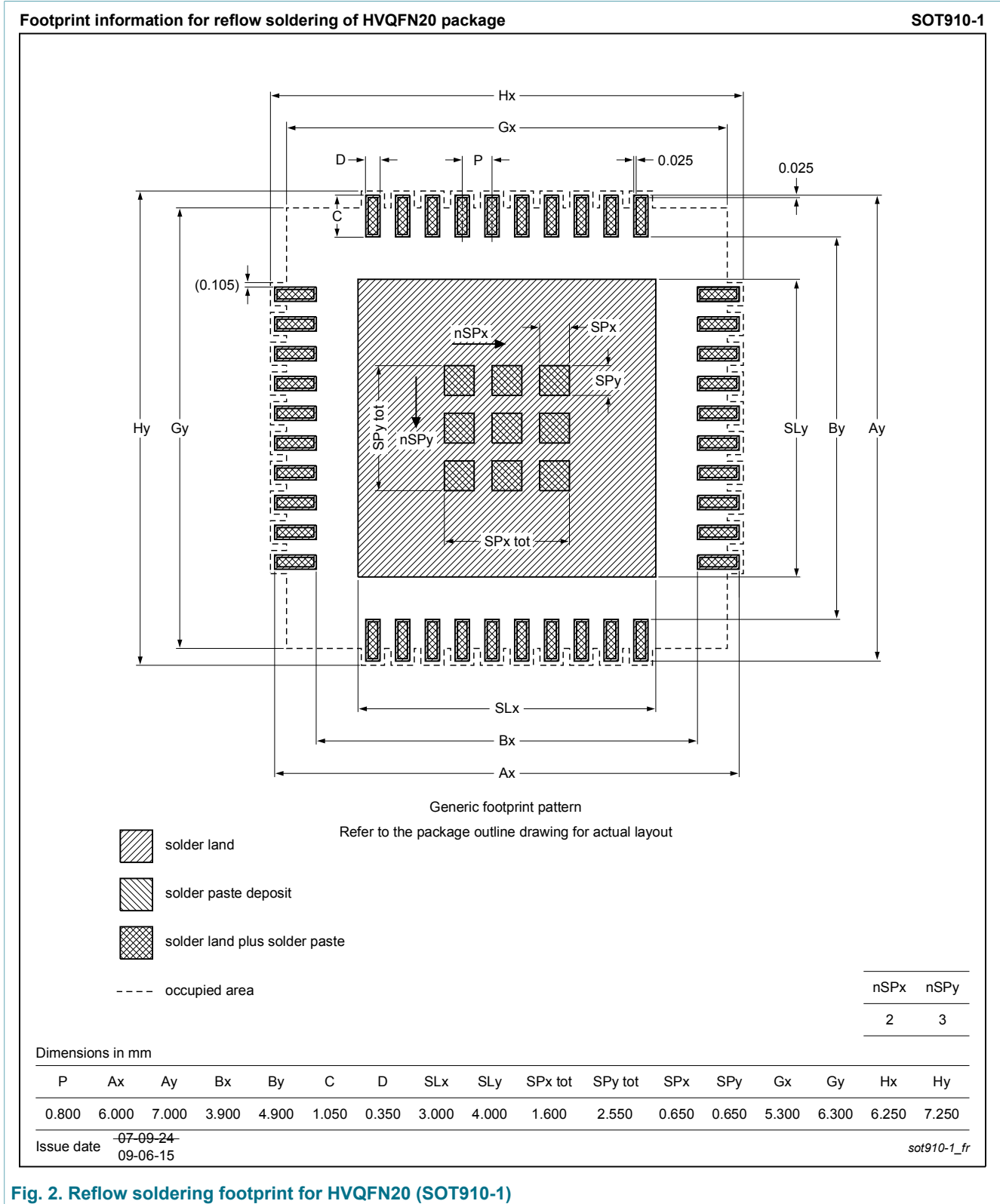


Fig. 2. Reflow soldering footprint for HVQFN20 (SOT910-1)

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## 4. Legal information

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Date of release: 8 February 2016

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